



**BOARD LEVEL COOLING - Extruded 6374**

Extruded 6374 is a dual radial board level heat sink designed to cool TO-218, TO-220, TO-247, Multiwatt, and SIP devices. Representative image only.

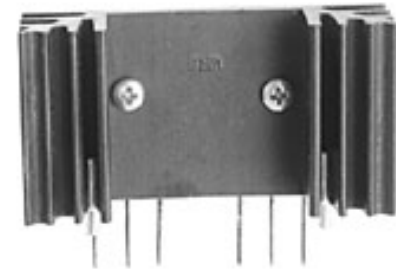
**ORDERING INFORMATION**

| Part Number | Device Type                            |
|-------------|--|
| 6374BG      | TO-218, TO-220, TO-247, Multiwatt, SIP |

**HEAT SINK DETAILS**

| Property                   | Details               |
|----------------------------|-----------------------|
| Material                   | Aluminum              |
| Finish                     | Black Anodize         |
| Device Attachment Options  | Requires Mounting Kit |
| Thermal Interface Material | -                     |

| Property                     | Details  |
|------------------------------|----------|
| Heat Sink Width (mm)         | 59.99    |
| Heat Sink Length (mm)        | 16.00    |
| Heat Sink Height (mm)        | 31.75    |
| Heat Sink Mounting Direction | Vertical |



**MECHANICAL & PERFORMANCE**

Drawing dimensions are shown in mm, (in)

| Part Number | "X" Dim       | "Y" Dim      | "Z" Dim      |
|-------------|---------------|--------------|--------------|
| 6374BG      | 19.05 (0.750) | 5.08 (0.200) | 2.67 (0.105) |

Mounting Details:

